DATA SHEET

NEC

COMPOUND FIELD EFFECT POWER TRANSISTOR

μPA1523B

P-CHANNEL POWER MOS FET ARRAY
SWITCHING
INDUSTRIAL USE

DESCRIPTION

The μPA1523B is P-channel Power MOS FET Array that built in 4 circuits designed for solenoid, motor and lamp driver.

FEATURES

- Full Mold Package with 4 Circuits
- –4 V driving is possible
- Low On-state Resistance
  $R_{DS(on)1}$ = 0.8 Ω MAX. (@V_{GS} = –10 V, I_D = –1 A)
  $R_{DS(on)2}$ = 1.3 Ω MAX. (@V_{GS} = –4 V, I_D = –1 A)
- Low Input Capacitance Ciss = 190 pF TYP.

ORDERING INFORMATION

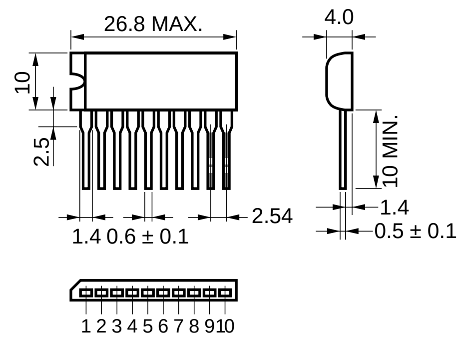
Type Number	Package
μPA1523BH	10 Pin SIP

ABSOLUTE MAXIMUM RATINGS (T_A = 25 ˚C)

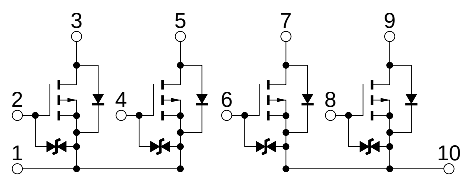
Drain to Source Voltage (V_{GS} = 0)	V_{DSS}	–60	V
Gate to Source Voltage (V_{DS} = 0)	$V_{GSS(AC)}$	∓20	V
Drain Current (DC)	$I_{D(DC)}$	∓2.0	A/unit
Drain Current (pulse)	$I_{D(pulse)}$ *1	∓8.0	A/unit
Total Power Dissipation	P_{T1} *2	28	W
Total Power Dissipation	P_{T2} *3	3.5	W
Channel Temperature	T_{CH}	150	˚C
Storage Temperature	T_{stg}	–55 to + 150	˚C
Single Avalanche Current	I_{AS} *4	–2.0	A
Single Avalanche Energy	E_{AS} *4	0.4	mJ

*1 PW ≤ 10 μs, Duty Cycle ≤ 1%
*2 4 Circuits, T_C = 25 ˚C
*3 4 Circuits, T_A = 25 ˚C
*4 Starting T_{CH} = 25 ˚C, V_{DD} = –30 V, V_{GS} = –20 V → 0, R_G = 25 Ω, L = 100 μH

PACKAGE DIMENSIONS
in millimeters



CONNECTION DIAGRAM



ELECTRODE CONNECTION
2, 4, 6, 8: Gate
3, 5, 7, 9: Drain
1, 10 : Source

Build-in Gate Diodes are for protection from static electricity in handing.
In case high voltage over V_{GSS} is applied, please append gate protection circuits.

The information in this document is subject to change without notice.

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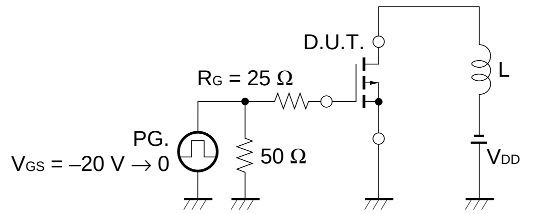
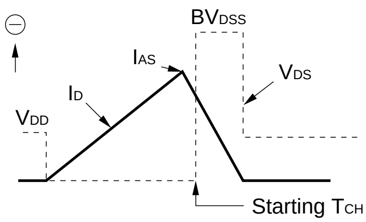
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

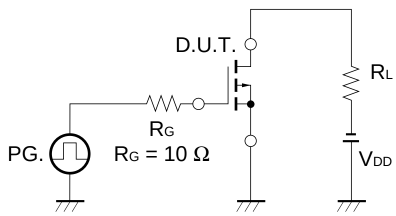
CHARACTERISTIC	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Leakage Current	I_{DSS}	V_{DS} = –60 V, V_{GS} = 0			–10	μA
Gate Leakage Current	I_{GSS}	V_{GS} = ∓20 V, V_{DS} = 0			∓10	μA
Gate Cutoff Voltage	$V_{GS(off)}$	V_{DS} = –10 V, I_D = –1.0 mA	–1.0		–2.0	V
Forward Transfer Admittance	$\| Y_{fs} \|$	V_{DS} = –10 V, I_D = –1.0 A	0.8			S
Drain to Source ON-Resistance	$R_{DS(on)1}$	V_{GS} = –10 V, I_D = –1.0 A		0.5	0.8	Ω
Drain to Source ON-Resistance	$R_{DS(on)2}$	V_{GS} = –4.0 V, I_D = –1.0 A		0.8	1.3	Ω
Input Capacitance	C_{iss}	V_{DS} = –10 V, V_{GS} = 0, f = 1.0 MHz		190		pF
Output Capacitance	C_{oss}			115		pF
Reverse Transfer Capacitance	C_{rss}			43		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = –1.0 A, $V_{GS(on)}$ = –10 V,		8		ns
Rise Time	t_r	V_{DD} ≒ –30 V, R_L = 30 Ω		53		ns
Turn-off Delay Time	$t_{d(off)}$			400		ns
Fall Time	t_f			230		ns
Total Gate Charge	Q_G	V_{GS} = –10 V, I_D = –2.0 A, V_{DD} = –48 V		10		nC
Gate to Source Charge	Q_{GS}			1.1		nC
Gate to Drain Charge	Q_{GD}			3.5		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 2.0 A, V_{GS} = 0		1.0		V
Reverse Recovery Time	t_{rr}	I_F = 2.0 A, V_{GS} = 0, di/dt = 50 A/μs		180		ns
Reverse Recovery Charge	Q_{rr}			250		nC

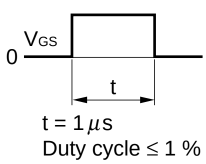
Test Circuit 1 Avalanche Capability

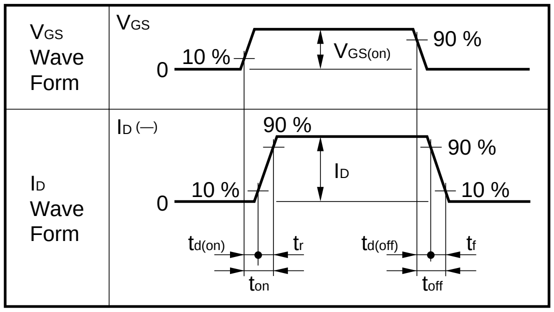




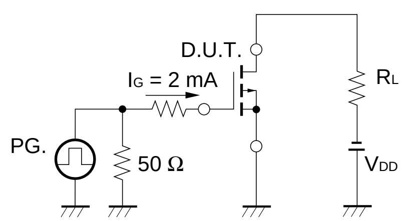
Test Circuit 2 Switching Time





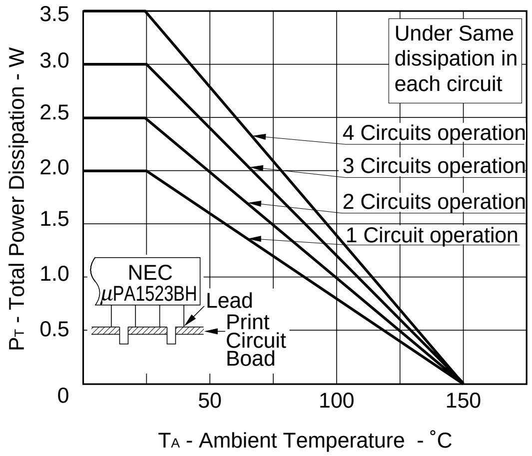


Test Circuit 3 Gate Charge

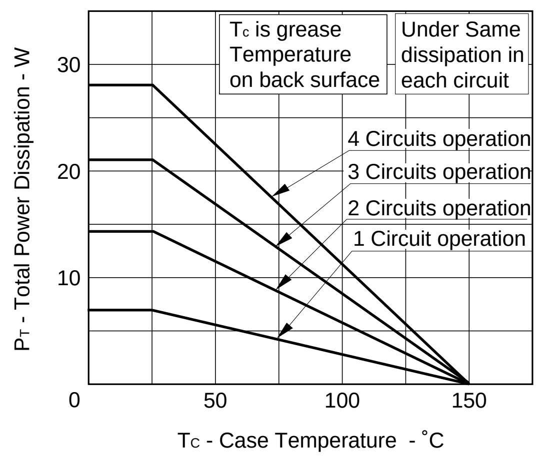


TYPICAL CHARACTERISTICS (T_A = 25 ˚C)

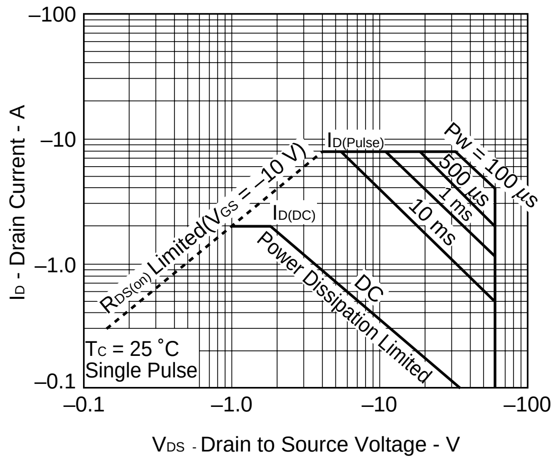
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



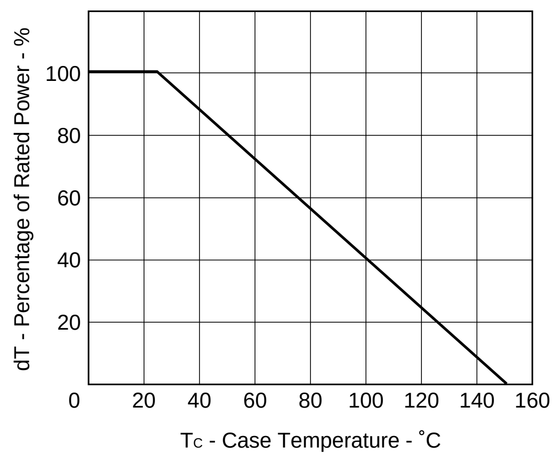
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



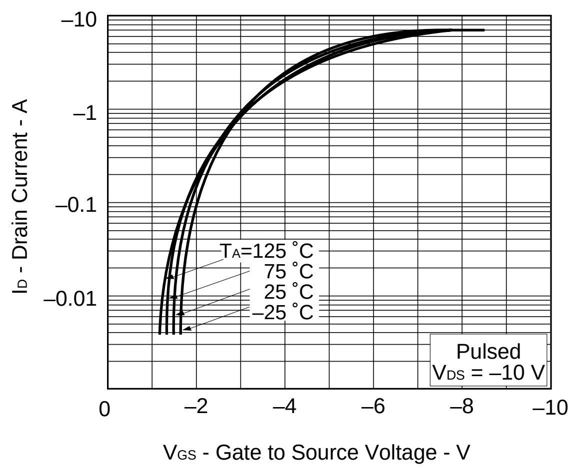
FORWARD BIAS SAFE OPERATING AREA



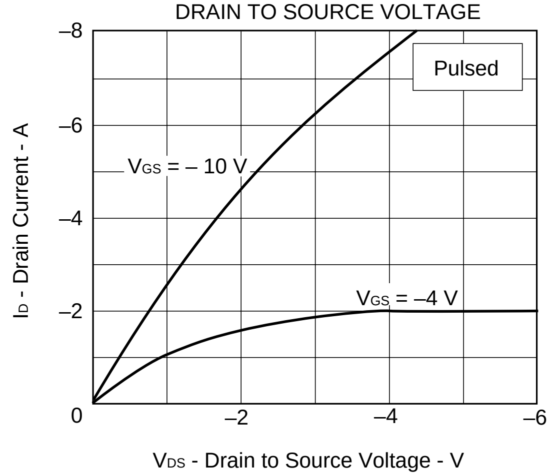
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



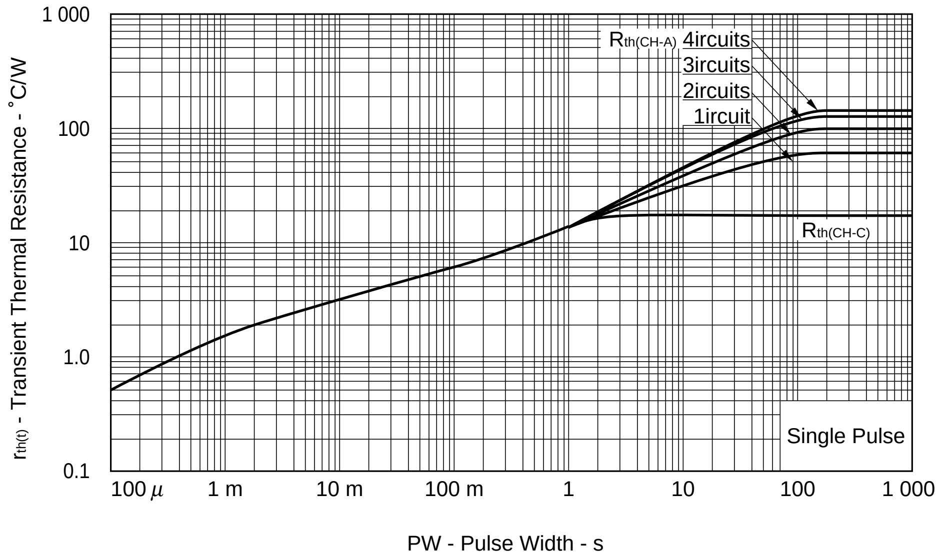
FORWARD TRANSFER CHARACTERISTICS



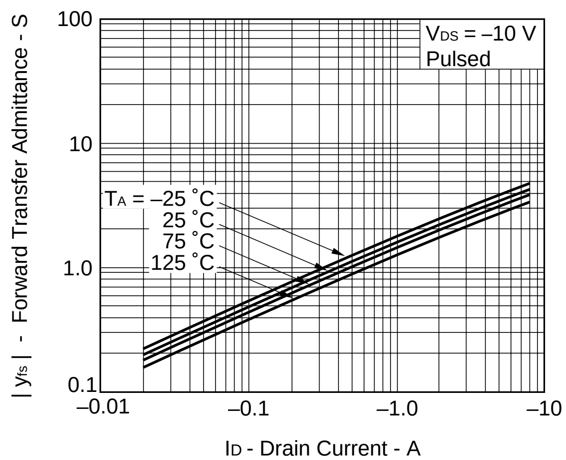
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



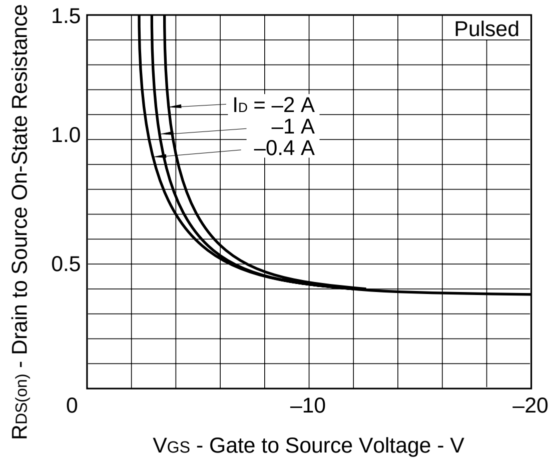
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



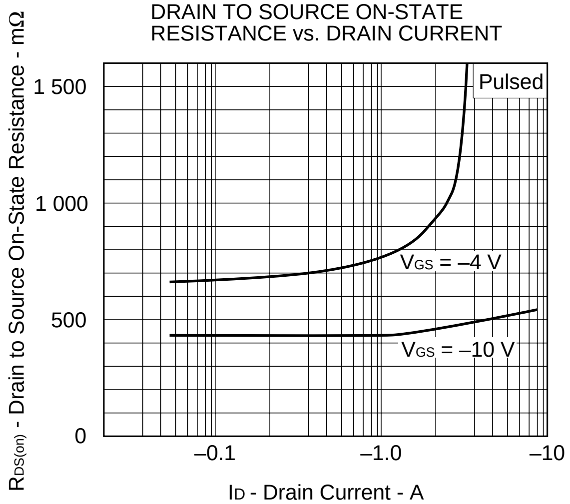
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



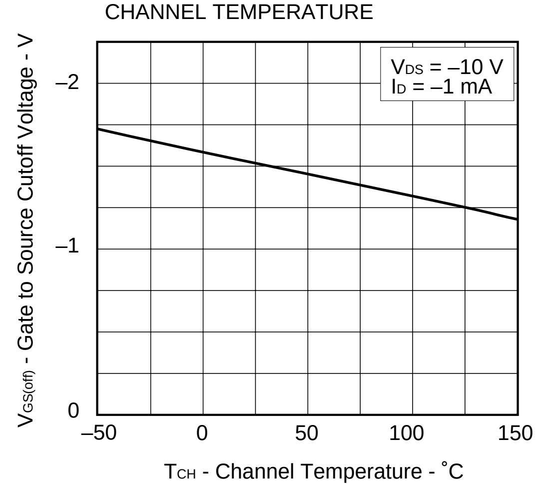
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



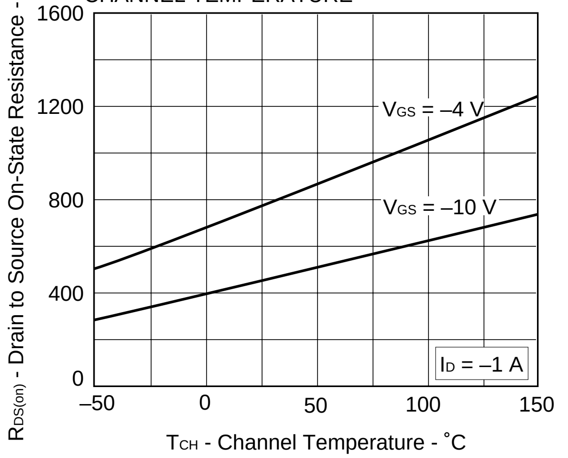
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



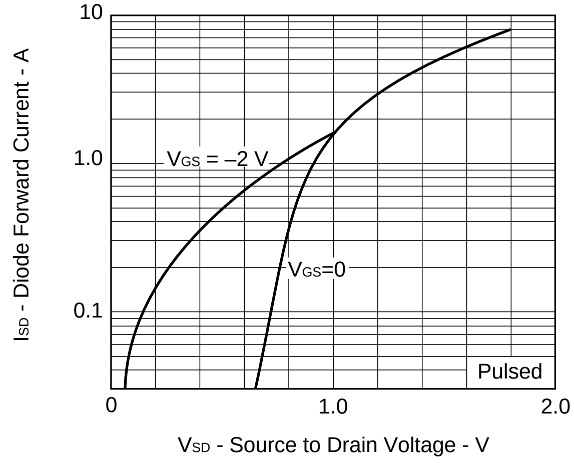
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



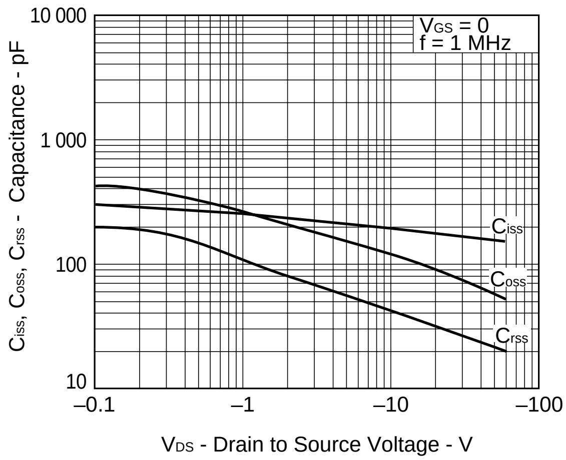
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



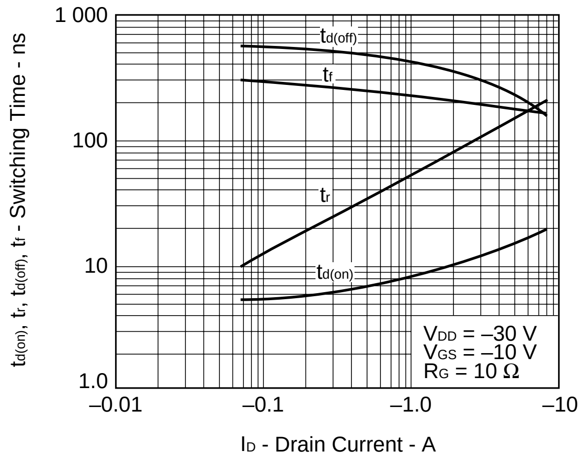
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



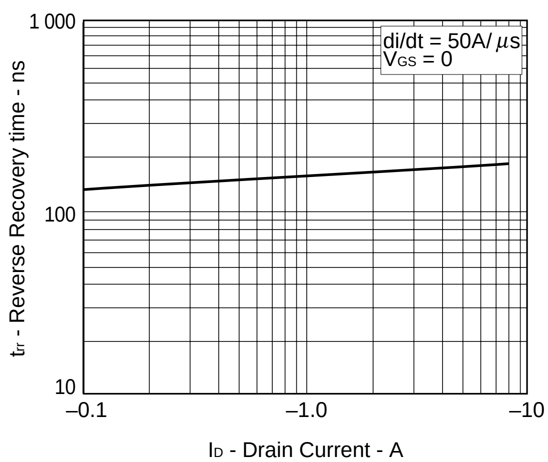
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



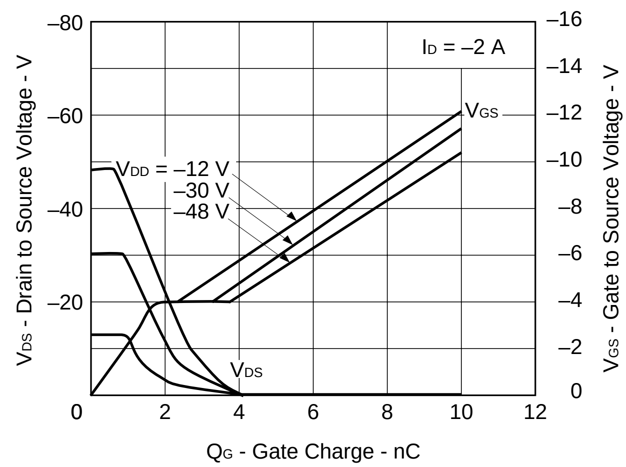
SWITCHING CHARACTERISTICS

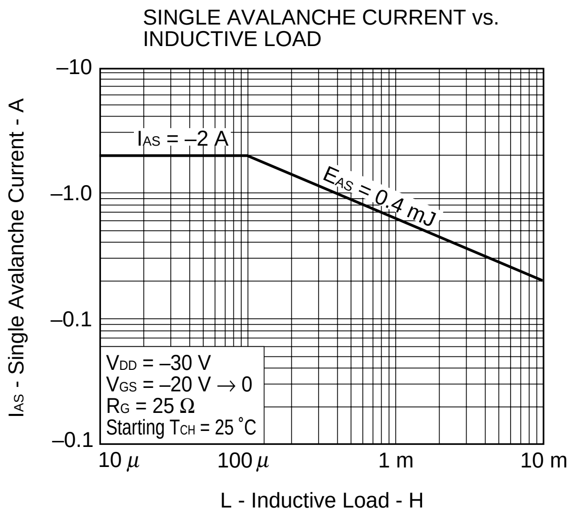


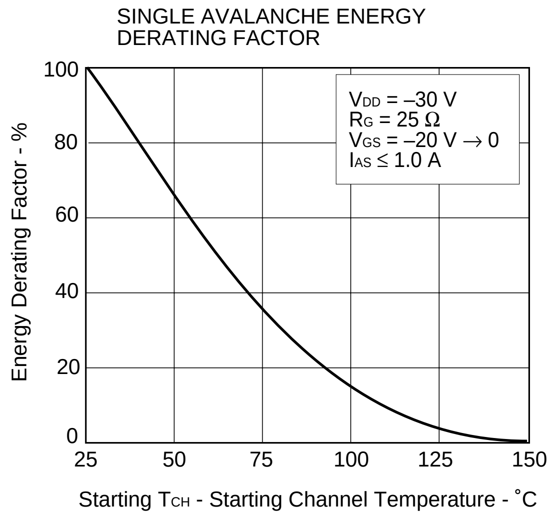
REVERSE RECOVERY TIME vs. DRAIN CURRENT



DYNAMIC INPUT/OUTPUT CHARACTERISTICS







REFERENCE

Document Name	Document No.
NEC semiconductor for device reliability/quality control system	TEI-1202
Quality grade on NEC semiconductor devices	IEI-1209
Semiconductor device mounting technology manual	C10535E
Semiconductor device package manual	C10943X
Guide to quality assurance for semiconductor devices	MEI-1202
Semiconductor selection guide	X10679E
Power MOS FET features and application switching power supply	TEA-1034
Application circuits using Power MOS FET	TEA-1035
Safe operating area of Power MOS FET	TEA-1037

[MEMO]